



# SOT363

plastic, surface-mounted package; 6 leads; 0.65 mm pitch; 2 mm x 1.25 mm x 0.95 mm body

9 May 2018

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	TSSOP6
<b>Package type industry code</b>	TSSOP6
<b>Package style descriptive code</b>	TSSOP (thin shrink small outline package)
<b>Package body material type</b>	P (plastic)
<b>JEITA package outline code</b>	SC-88
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	16-3-2006
<b>Manufacturer package code</b>	SOT363

Table 1. Package summary

Parameter	Min	Typ	Nom	Max	Unit
package length	1.8	-	2	2.2	mm
package width	1.15	-	1.25	1.35	mm
seated height	0.8	-	0.95	1.1	mm
nominal pitch	-	-	0.65	-	mm
actual quantity of termination	-	-	6	-	A/A



## 2. Package outline

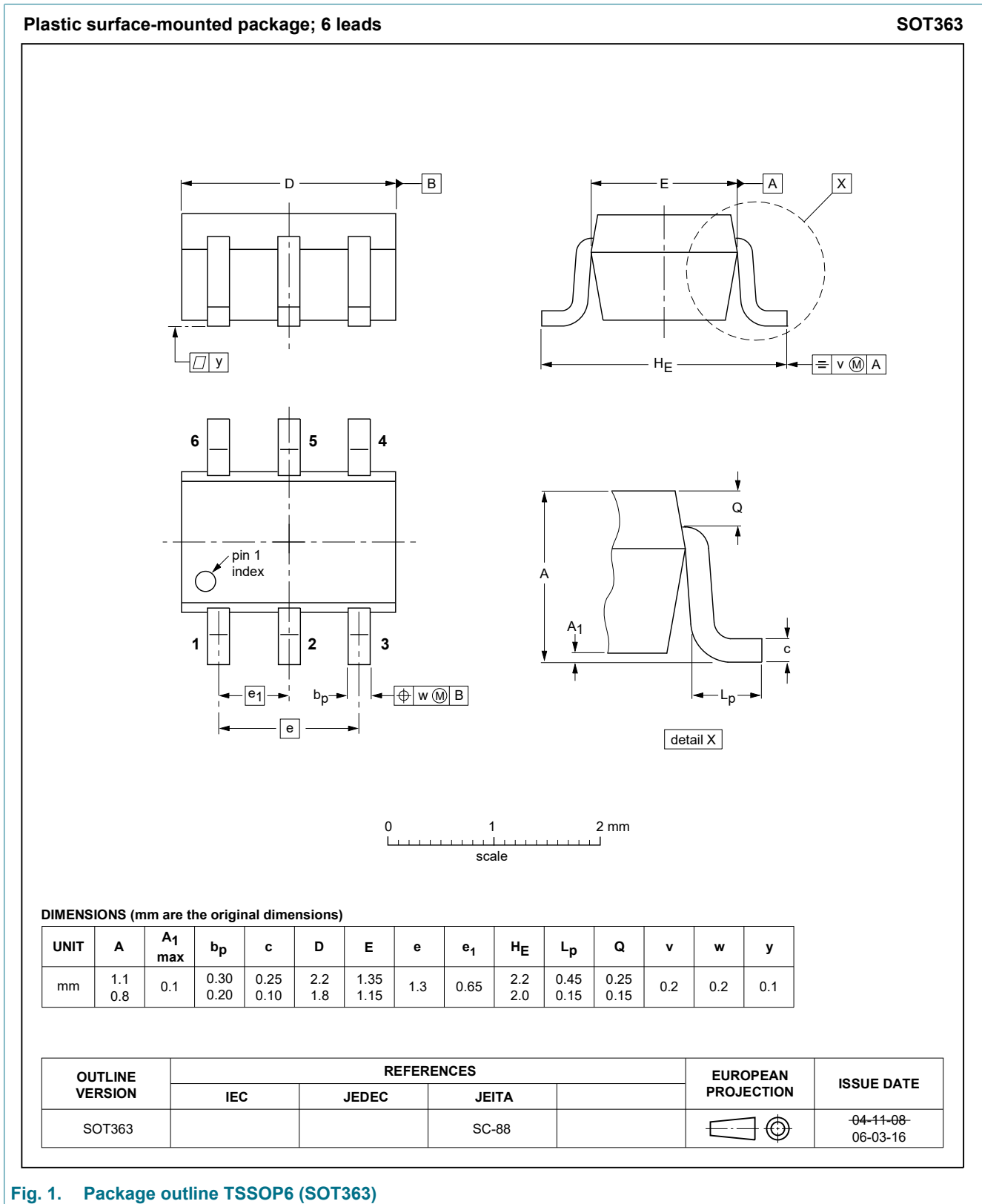


Fig. 1. Package outline TSSOP6 (SOT363)

### 3. Soldering

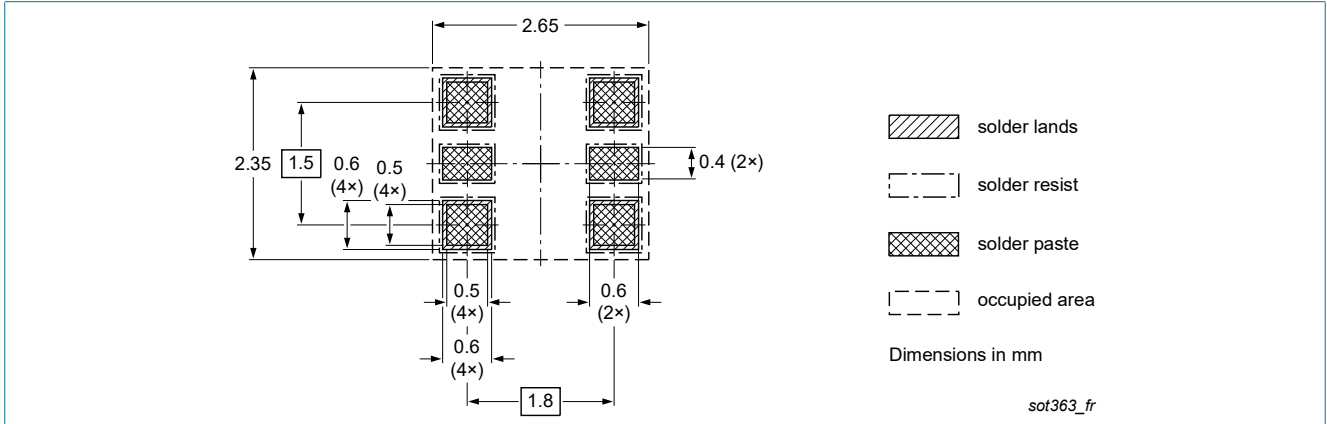


Fig. 2. Reflow soldering footprint for TSSOP6 (SOT363)

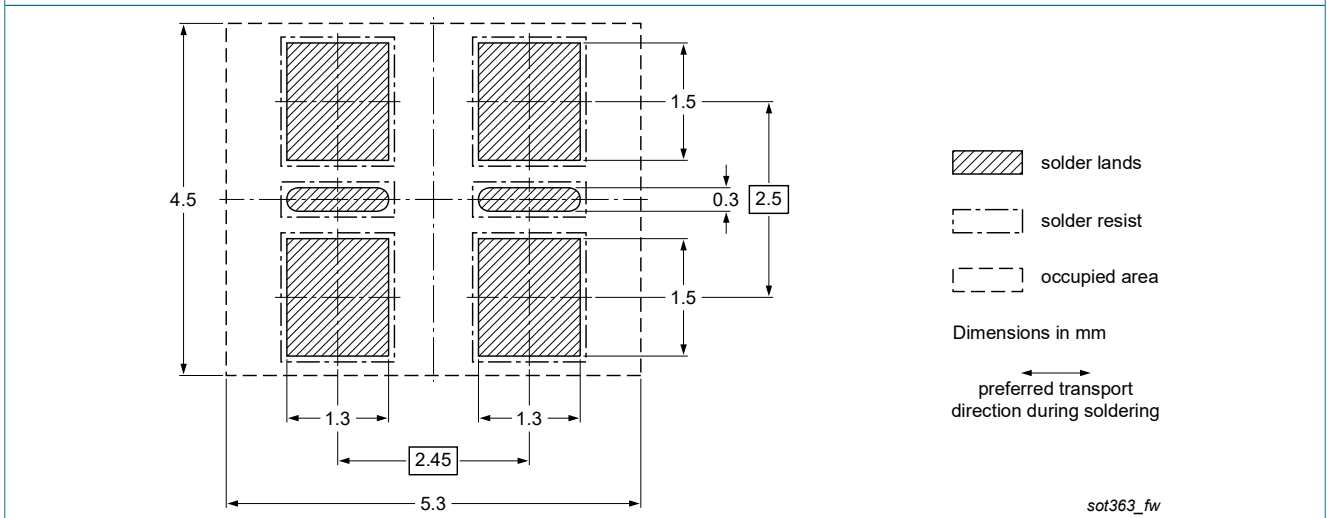


Fig. 3. Wave soldering footprint for TSSOP6 (SOT363)

## 4. Legal information

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Date of release: 9 May 2018

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